

**Electromagnetic Simulation Software** 

# Simulation of Electrostatic Discharge (ESD) Testing with XFdtd<sup>®</sup>

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2019

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# Overview



- 1. Static Electricity and Electrostatic Discharge (ESD)
- 2. Electrostatic Discharge Testing
- 3. ESD Testing Simulation with XFdtd
- 4. Conclusions



# **Static Electricity**

# 2019

### Causes:

- Contact / Triboelectric
- Pressure / Piezoelectric
- Temperature / Pyroelectric
- Charge / Electrostatic Induction





## **Triboelectric Charge**



#### **Triboelectric Charge Triboelectric Charge** Material Material Contact Separation **+**+ t. **+**+ ++ Material "A" Material "B" Material "A" Material "B" Net = 0Net = 0Net = +1Net =

Source: [1]

REMC

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# **Triboelectric Charge**

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q = CV

- q Charge (Coulombs) C – Capacitance (Farads)
- *V* Voltage (Volts)

$$E = \frac{1}{2}CV^{2}$$
  
E - Energy (joules)

| Examples of Static Generation - Typical Voltage Levels |           |           |  |  |  |
|--|-----------|-----------|--|--|--|
| Means of Generation                                    | 10-25% RH | 65-90% RH |  |  |  |
| Walking Across Carpet                                  | 35,000V   | 1,500V    |  |  |  |
| Walking Across Vinyl Tile                              | 12,000V   | 250V      |  |  |  |
| Worker at a Bench                                      | 6,000V    | 100V      |  |  |  |
| Poly Bag Picked up from Bench                          | 20,000V   | 1,200V    |  |  |  |
| Chair with Urethane Foam                               | 18,000V   | 1,500V    |  |  |  |

Source: [1]

## Electrostatic Discharge

# 2019



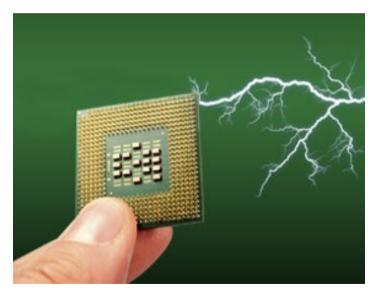
## **ESD** Cost



"... in the electronics industry, losses associated with ESD are estimated at between a half billion and five billion dollars annually."

- In reality, total ESD cost is very difficult to determine.
- Facts:
  - Multiple Prototypes
  - Warranty Claims
  - Loss of Consumer Confidence

Reference: [2]





# **ESD** Testing

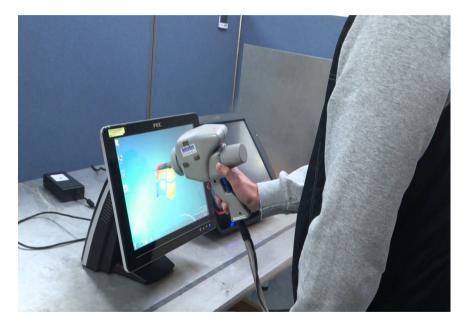
# 2019

### Standards:

• ANSI/ESD, IEC, JEDEC, MIL, etc.

Common Test Models:

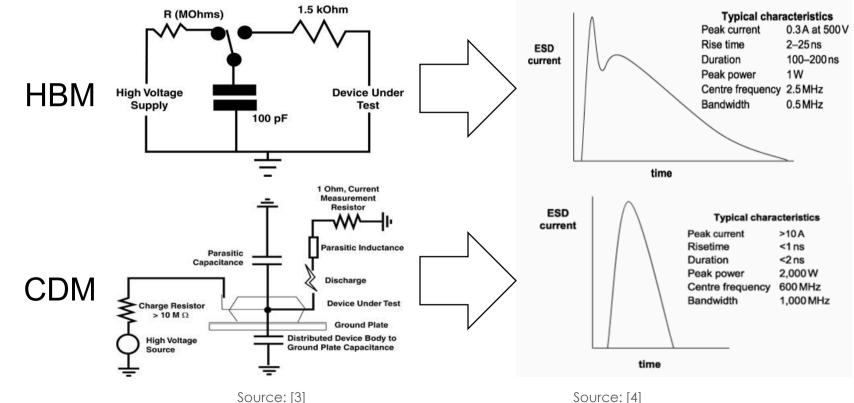
- Human Body Model (HBM)
- Charged Device Model (CDM)
- Machine Model (MM)





### **HBM & CDM Models**





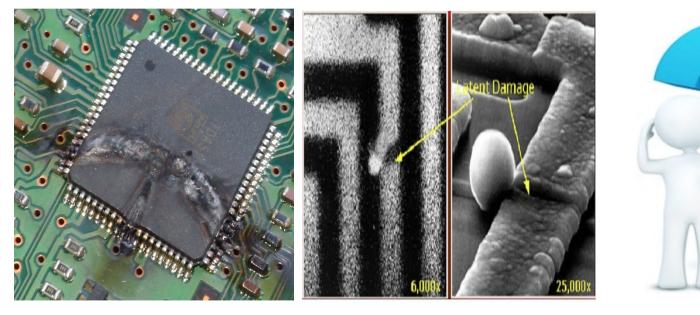
## **ESD** Damage

# 2019

### Catastrophic

#### Latent

### Upset



# XFdtd ESD Simulation



### <u>Goals:</u>

- Help engineers pinpoint locations in their designs at risk of experiencing dielectric breakdown during ESD testing.
- Help engineers pinpoint components at risk of damage during ESD testing.
- Allow engineers to optimize their ESD mitigation designs prior to hardware prototyping.
- Reduce product development costs and time to market.
- Improve product reliability and consumer confidence.

# New XFdtd Functionality

- ESD Waveforms
  > HBM, CDM, MM, etc.
- Material Parameter
  Dielectric Strength
- Result Sensor
  - Dielectric Breakdown
- Circuit Components
  Rated Voltage/Current

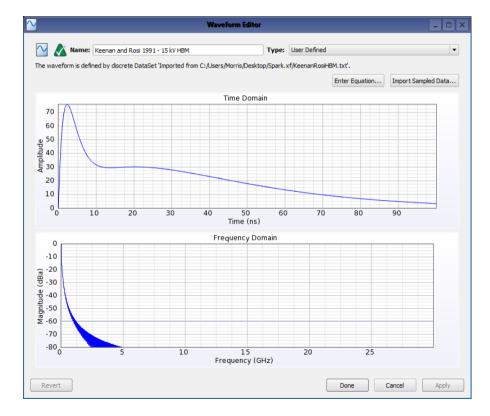




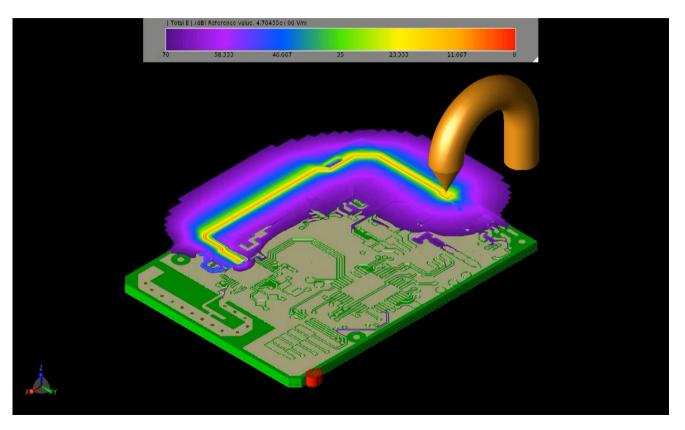
# ESD Waveforms

**2019** 

- ESD waveforms can be imported using XFdtd's improved User Defined Waveform feature.
- <u>Waveform References:</u>
  [5] Cerri et al., 1996
  [6] Keenan and Rosi, 1991
  [7] Songlin et al., 2003
  [8] Yuan et al., 2006
  [9] Wang et al., 2003
  [10] Berghe and Zutter, 1998



### **ESD Testing Electric Fields**





## **Dielectric Strength**

- Defines the maximum electric field a material can withstand without experiencing dielectric breakdown and losing its insulating properties.
- Materials with an infinite dielectric strength will be ignored by the Dielectric Breakdown Sensor.

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Apply

#### Å **Material Editor** Name: Substrate Type: Physical Ŧ Electric: Isotropic Magnetic: Free Space • Electric Physical Parameters Appearance Notes Type: Nondispersive • -Entry Method: Normal Good Conductor: Automatic 💌 Surface Conductivity Correction Conductivity: 0.001 S/m Relative Permittivity: 4.2 Infinite Dielectric Strength Dielectric Strength: 2e+07 V/m

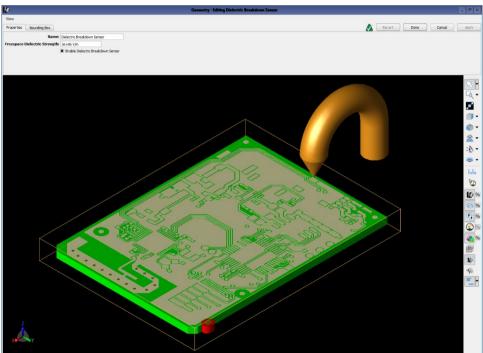
Done

Revert

Cancel

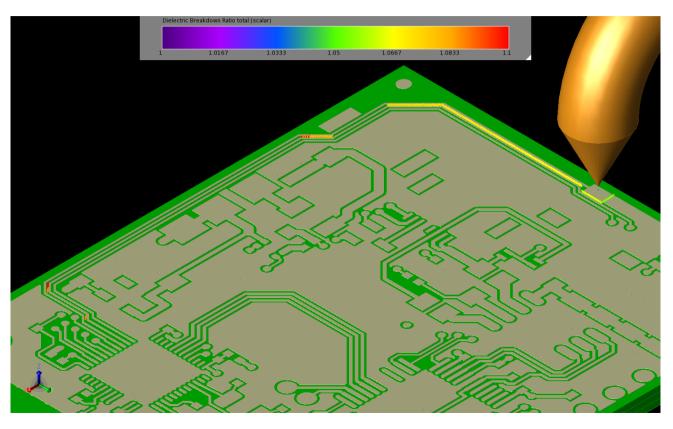
# **Dielectric Breakdown Sensor**

- Computational savings can be obtained by reducing the size of the sensor to the geometry's bounding box or to specific regions of interest.
- The default dielectric strength of free space is set to 3.0 MV/m corresponding to air at sea level.





### **Dielectric Breakdown Risk**





# **Rated Components**

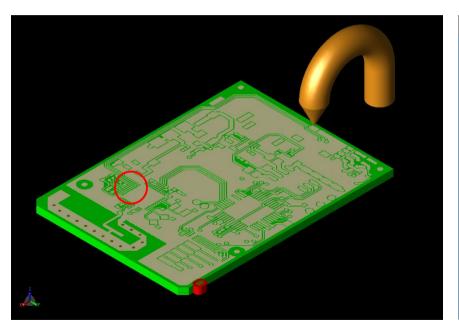
- Rated peak voltages and currents can be obtained from a circuit component's data sheet and entered into its Circuit Component Definition.
- Infinite rated voltages and currents will be ignored by XFdtd's System Sensor.

|                  | Circuit Comp                                | ponent Definition Editor | - • ×    |
|------------------|---|--------------------------|----------|
| 뺍 🚺 Name         | e: 50 Ohm Resistor                          | Type: Passive Load       | •        |
| Resistance:      | 50 ohm                                      | RLC Specification: Norm  | nal 🔻    |
| Inductance:      | 0 nH  |                          | 0        |
| Capacitance:     | 0 pF  |                          |          |
| RLC Arrangen     | All Series<br>nent: All Parallel<br>RL    C |                          | <u> </u> |
| -Rated Voltage & |   |                          |          |
| Rated Voltage    |   | Infinite Rated Voltage   |          |
| Rated Curren     | t: inf A                                    | X Infinite Rated Current |          |
| Revert           |   | Done Cancel              | Apply    |



## **Exceeded Design Specs**





| Max Component Voltages and Currents Results for Remote : 000008 : 1   |             |               |             |               |  |  |
|---|-------------|---------------|-------------|---------------|--|--|
| ile   |             |               |             |               |  |  |
| Max Component Voltages and Currents Results for:      Run Details        Project Name:      Remote        Simulation:      HBM Test (Coarse Staircase, Reduced Dielectric Strength)        Run Number:      1 |             |               |             |               |  |  |
| Component Name /  | Max Voltage | Rated Voltage | Max Current | Rated Current |  |  |
| C1  | 17.7892 V   | 16 V          | 0.170955 A  |               |  |  |
| C2  | 2.55162 V   | 16 V          | 0.0439905 A |               |  |  |
| C3  | 9.12234 V   | 16 V          | 0.154973 A  |               |  |  |
| ESD Feed  | 392.368 V   |               | 5.34214 A   |               |  |  |
| L1  | 1.42421 V   |               | 0.572944 A  | 0.44 A        |  |  |
| L2  | 0.9173 V    |               | 0.268556 A  | 0.44 A        |  |  |
| L3  | 1.08432 V   |               | 0.134515 A  | 0.44 A        |  |  |
| R1  | 20.1895 V   | 30 V          | 0.40379 A   |               |  |  |
| R2  | 64.1534 V   | 30 V          | 1.28307 A   |               |  |  |
| R3  | 278.358 V   | 30 V          | 5.56717 A   |               |  |  |



# **Optimize ESD Mitigation**

- Once locations and components at risk of suffering ESD damage are pinpointed, the ESD mitigation design can be optimized:
  - Increase distance between traces
  - Reduce sharp angles and edges
  - Use materials with higher dielectric strength
  - Introduce ESD protection circuits and/or suppressors
  - Improve shielding
  - Use quality components with higher rated values



# Conclusions



- ESD simulation does not replace hardware testing.
- ESD simulation does allow engineers to predict potential ESD problems and optimize ESD protection in the design phase.
  - Reduce number of hardware prototypes
  - Reduce product development cost
  - Reduce time to market
  - Improve product reliability
- This is only beginning...Multiphysics ESD Analysis
  - Spark Discharge Simulation
  - Thermal Damage Simulation

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# **Contact Us**



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